

#### **Bi-directional Ultra Low Capacitance TVS Diode**

• ESD / transient protection of RF signal

lines according to:

IEC61000-4-2 (ESD): ±20kV (contact)

IEC61000-4-4 (EFT): 40 A (5 / 50 ns)

IEC61000-4-5 (Surge): 3 A (8 / 20 μs)

 Extremely small form factor down to 0.62 x 0.32 x 0.31 mm³

Very low dynamic resistance

Max. working voltage: ±5.3 V

• Extremely low capacitance: 0.2 pF typ.

• Very low reverse current < 1 nA typ.

• Very low series inductance down to 0.2 nH typ.

Pb-free (RoHS compliant) package

Qualified according AEC Q101

#### **Applications**

- ESD protection of sensitive RF signal lines
- RF antenna protection, frontend module
- GPS, mobile TV, FM radio, RKE, UWB





### ESD0P2RF-02LRH ESD0P2RF-02LS



| Туре           | Package   | Configuration          | Marking |
|----------------|-----------|------------------------|---------|
| ESD0P2RF-02LRH | TSLP-2-17 | 1 line, bi-directional | Т       |
| ESD0P2RF-02LS  | TSSLP-2-1 | 1 line, bi-directional | Т       |





**Maximum Ratings** at  $T_A = 25^{\circ}$ C, unless otherwise specified

| Parameter                                     | Symbol           | Value  | Unit |
|---|------------------|--------|------|
| ESD contact discharge <sup>1)</sup> , contact | V <sub>ESD</sub> | 20     | kV   |
| Peak pulse current $(t_p = 8 / 20 \mu s)^2$   | I <sub>pp</sub>  | 3      | Α    |
| Operating temperature range                   | $T_{op}$         | -55125 | °C   |
| Storage temperature                           | T <sub>stg</sub> | -55150 |      |

 $<sup>^{1}</sup>V_{\mathrm{ESD}}$  according to IEC61000-4-2

## **Electrical Characteristics** at $T_A = 25$ °C, unless otherwise specified

| Parameter  | Symbol         | Values |      |      | Unit |
|--|----------------|--------|------|------|------|
|  |                | min.   | typ. | max. |      |
| Characteristics -                                      | ,              |        |      |      | •    |
| Reverse working voltage                                | $V_{RWM}$      | -5.3   | -    | 5.3  | V    |
| Breakdown voltage                                      | $V_{(BR)}$     |        |      |      |      |
| $I_{(BR)}$ = 1 mA, from pin 2 to 1                     |                | 7      | -    | -    |      |
| $I_{(BR)}$ = 1 mA, from pin 1 to 2                     |                | 7      | -    | -    |      |
| Reverse current  | $I_{R}$        | -      | <1   | 50   | nA   |
| V <sub>R</sub> = 5.3 V                                 |                |        |      |      |      |
| Clamping voltage                                       | $V_{CL}$       |        |      |      | V    |
| $I_{PP} = 1 \text{ A}, t_p = 8/20 \ \mu \text{s}^{1)}$ |                | -      | 11   | <    |      |
| $I_{PP} = 3 \text{ A}, t_p = 8/20 \ \mu \text{s}^{1)}$ |                | -      | 16   | 21   |      |
| Diode capacitance                                      | C <sub>T</sub> |        |      |      | pF   |
| $V_{R} = 0 \text{ V}, f = 1 \text{ MHz}$               |                | -      | 0.23 | 0.4  |      |
| $V_{R} = 0 \text{ V}, f = 1 \text{ GHz}$               |                | -      | 0.2  | 0.4  |      |
| Dynamic resistance (tp=30ns)                           | $R_{D}$        | -      | 1    |      | Ω    |
| Series inductance                                      | L <sub>S</sub> |        |      |      | nH   |
| ESD0P2RF-02LS  |                | _      | 0.2  | _    |      |
| ESD0P2RF-02LRH   |                | _      | 0.4  | -    |      |

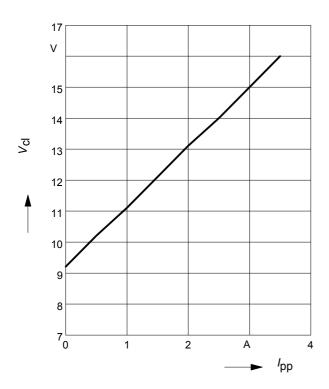
 $<sup>^{1}</sup>I_{pp}$  according to IEC61000-4-5

 $<sup>^2</sup>I_{
m pp}$  according to IEC61000-4-5



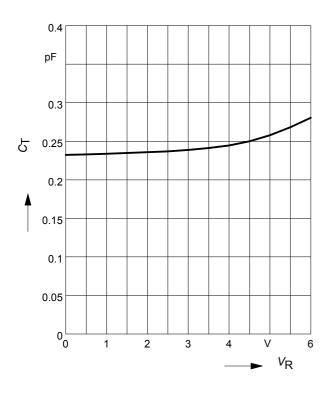
## Clamping voltage, $V_{cl} = f(I_{pp})$

$$t_{\rm p}$$
 = 8 / 20 µs



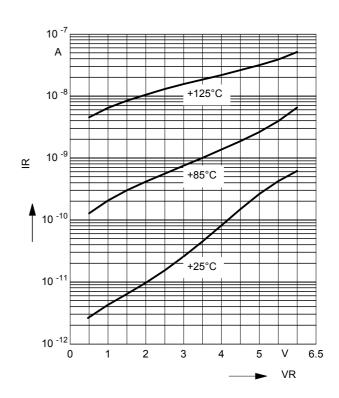
## Diode capacitance $C_T = f(V_R)$

$$f = 1MHz$$



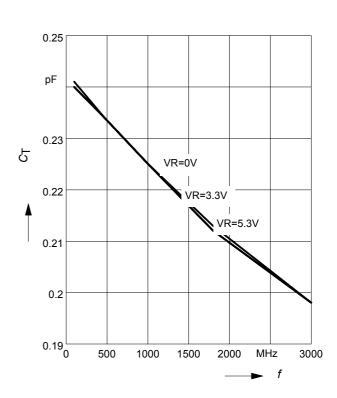
# Reverse current $I_R = f(V_R)$

## $T_A$ = Parameter



## Line capacitance $C_T = f(f)$

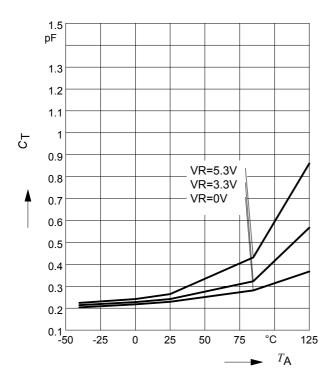
$$V_{R}$$
 = Parameter





## Line capacitance $C_T = f(T_A)$

 $V_{R}$  = Parameter, f = 1 MHz

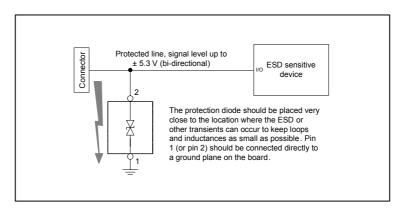


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## Application example ESD0P2RF...

1 line, bi-directional

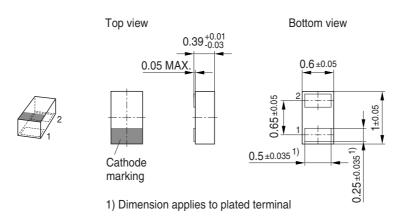


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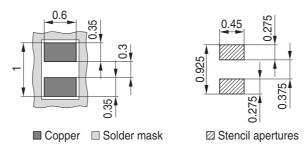


## Package Outline

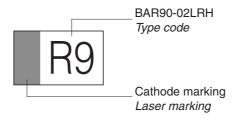


#### Foot Print

For board assembly information please refer to Infineon website "Packages"

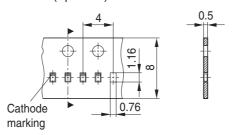


## Marking Layout (Example)



## Standard Packing

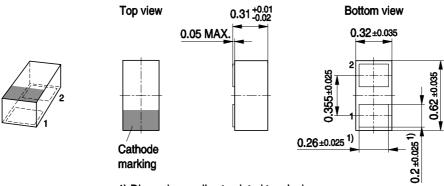
Reel ø180 mm = 15.000 Pieces/Reel Reel ø330 mm = 50.000 Pieces/Reel (optional)



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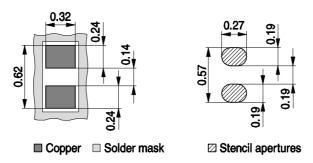
## Package Outline



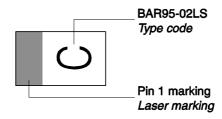
1) Dimension applies to plated terminal

#### **Foot Print**

For board assembly information please refer to Infineon website "Packages"

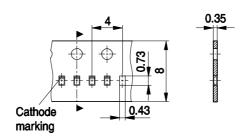


## Marking Layout (Example)



## Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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